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(12) **United States Design Patent**  
**Savandaiah et al.**

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(54) **DEPOSITION RING FOR A SEMICONDUCTOR PROCESSING CHAMBER**

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(73) Assignee: **APPLIED MATERIALS, INC.**, Santa Clara, CA (US)

(\*\*) Term: **15 Years**

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(51) **LOC (13) Cl.** ..... **15-09**

(52) **U.S. Cl.**  
USPC ..... **D15/138; D13/182**

(58) **Field of Classification Search**  
USPC ..... D23/249, 259, 262, 269; D15/138, 139, D15/143, 144, 144.1, 144.2, 150, 199;  
(Continued)

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(57) **CLAIM**

The ornamental design for a deposition ring for a semiconductor processing chamber, as shown and described.

**DESCRIPTION**

FIG. 1 is an enlarged top isometric view of a deposition ring for a semiconductor processing chamber, according to the first embodiment of the novel design.

FIG. 2 is a front elevation view thereof.

FIG. 3 is a back elevation view thereof.

FIG. 4 is a right elevation view thereof.

FIG. 5 is a left elevation view thereof.

FIG. 6 is a top plan view thereof.

FIG. 7 is a bottom plan view thereof.

FIG. 8 is an enlarged cross-sectional view thereof, taken along line 6-6 of FIG. 6.

FIG. 9 is an enlarged top isometric view of a deposition ring for a semiconductor processing chamber, according to the second embodiment of the novel design.

FIG. 10 is a front elevation view thereof.

FIG. 11 is a back elevation view thereof.

FIG. 12 is a right elevation view thereof.

FIG. 13 is a left elevation view thereof.

FIG. 14 is a top plan view thereof.

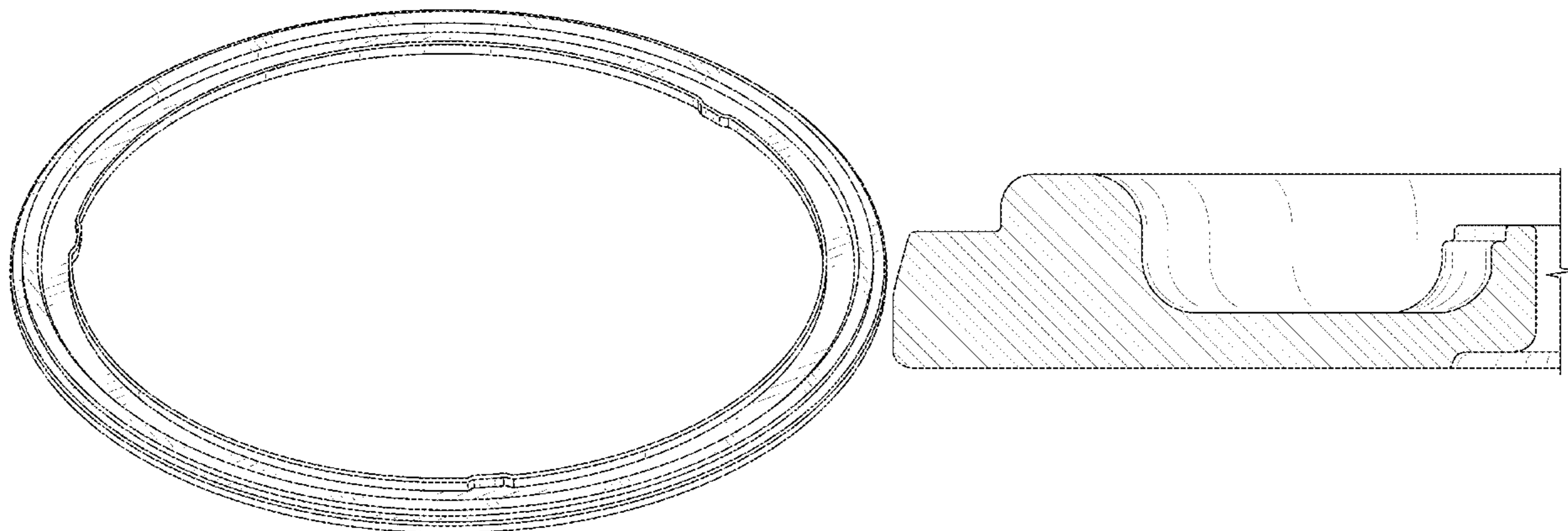
FIG. 15 is a bottom plan view thereof.

FIG. 16 is an enlarged cross-sectional view thereof, taken along line 16-16 of FIG. 14; and,

FIG. 17 is an enlarged cross-sectional view thereof, taken along line 17-17 of FIG. 14.

The dashed lines in FIGS. 1-9 represent unclaimed environment forming no part of the claimed design.

**1 Claim, 11 Drawing Sheets**



(58) **Field of Classification Search**

USPC ..... D13/118, 122, 133, 162, 182, 184, 199;  
 D22/113, 119  
 CPC ..... H01J 37/3414; H01J 37/3423; H01L  
 21/02631; H01L 2221/68363; H01L  
 2224/75186-75189; H01L 21/67742;  
 H01L 21/0226; H01L 21/02263; H01L  
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 21/02271; F16J 7/00; E04D 13/14; C23C  
 14/3407; C23C 14/35

See application file for complete search history.

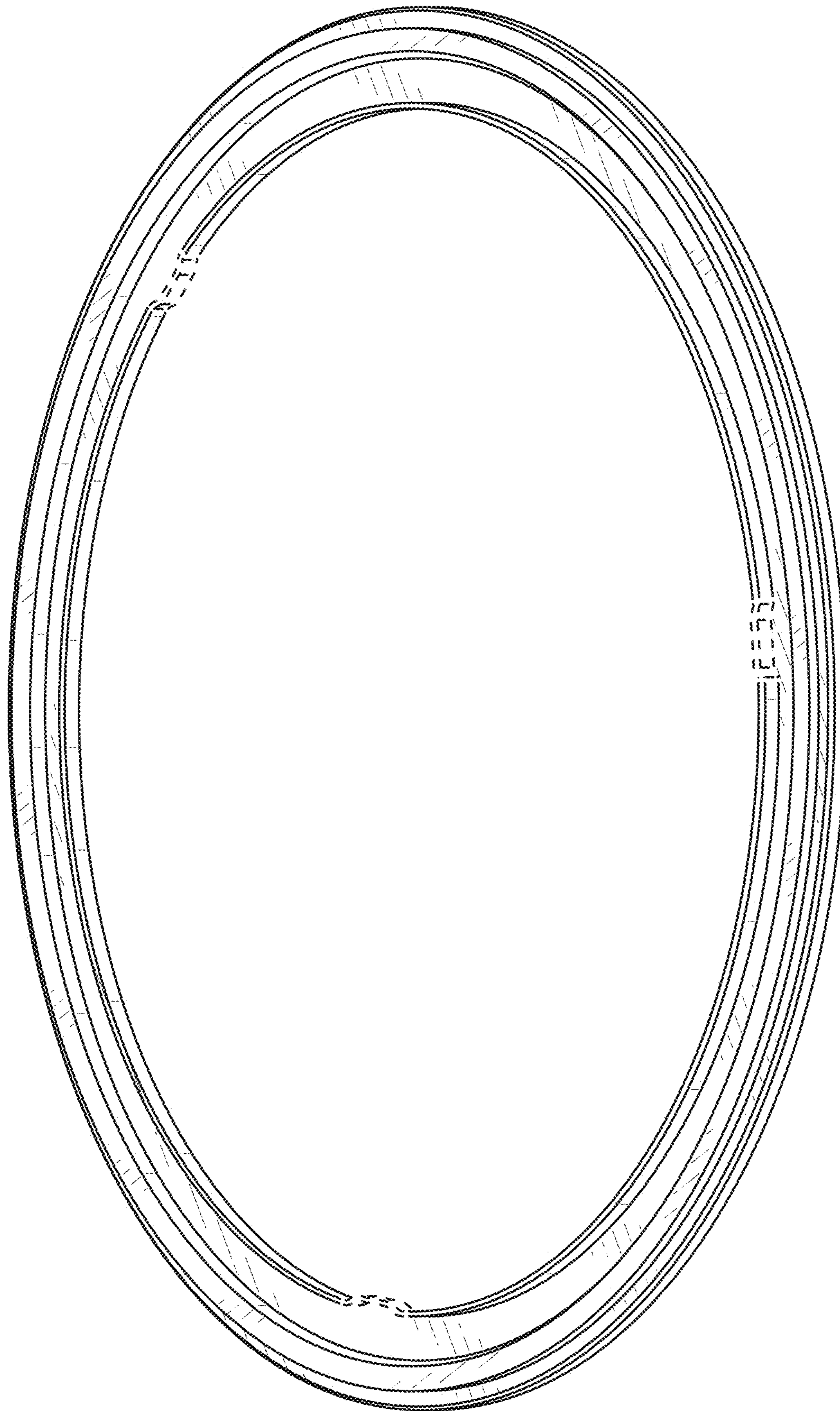
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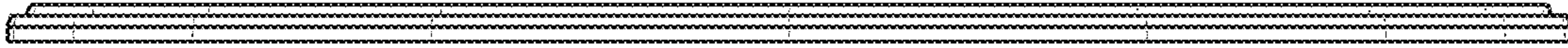
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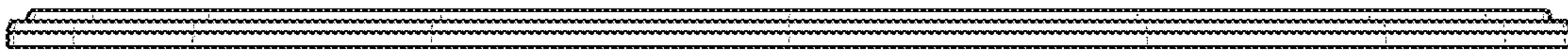
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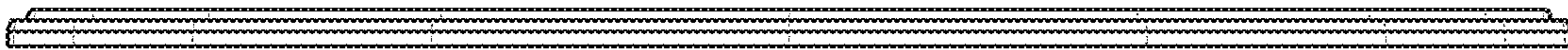
**FIG. 1**



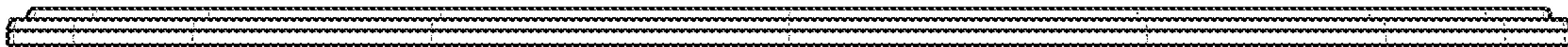
**FIG. 2**



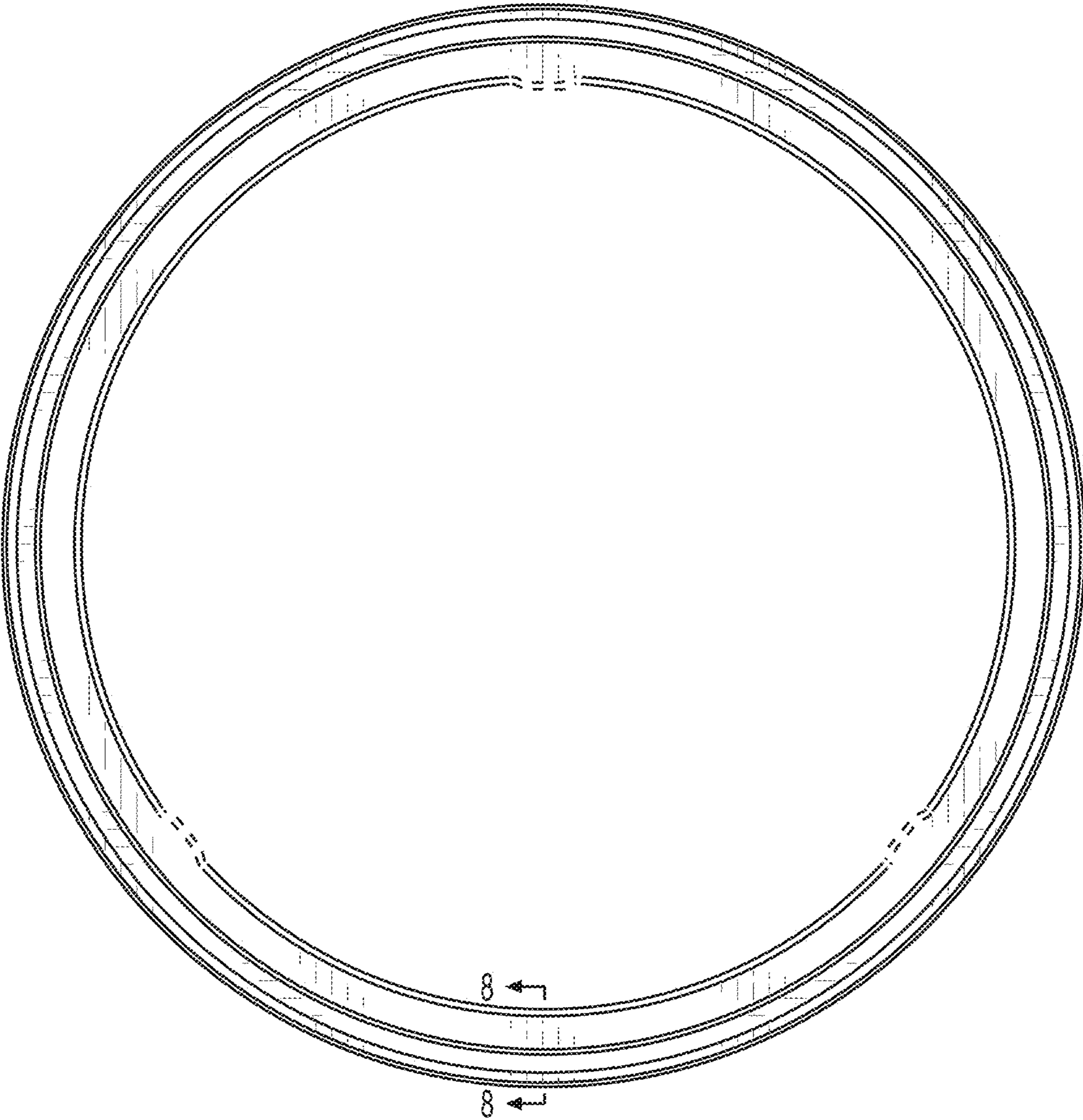
**FIG. 3**



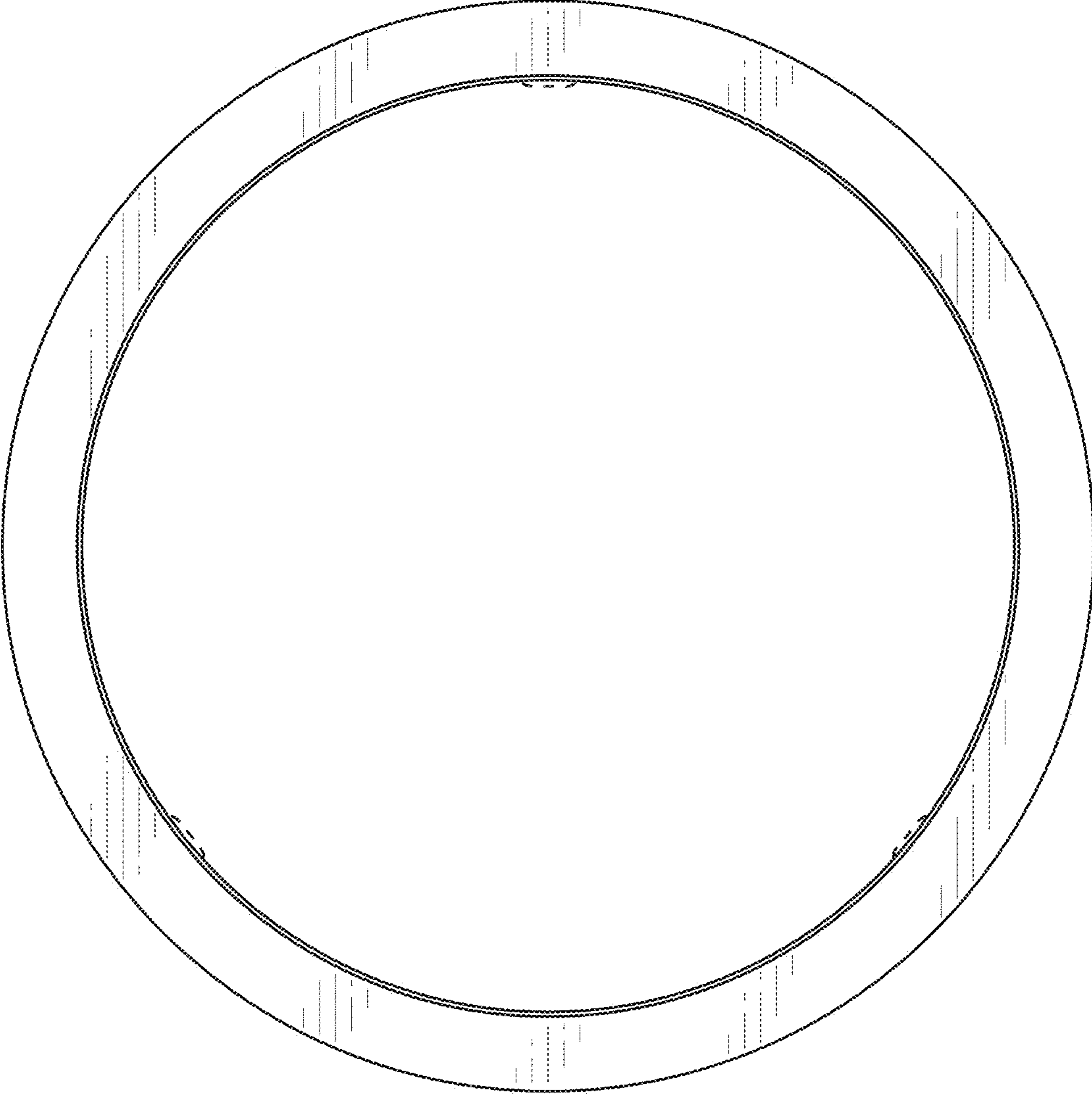
**FIG. 4**



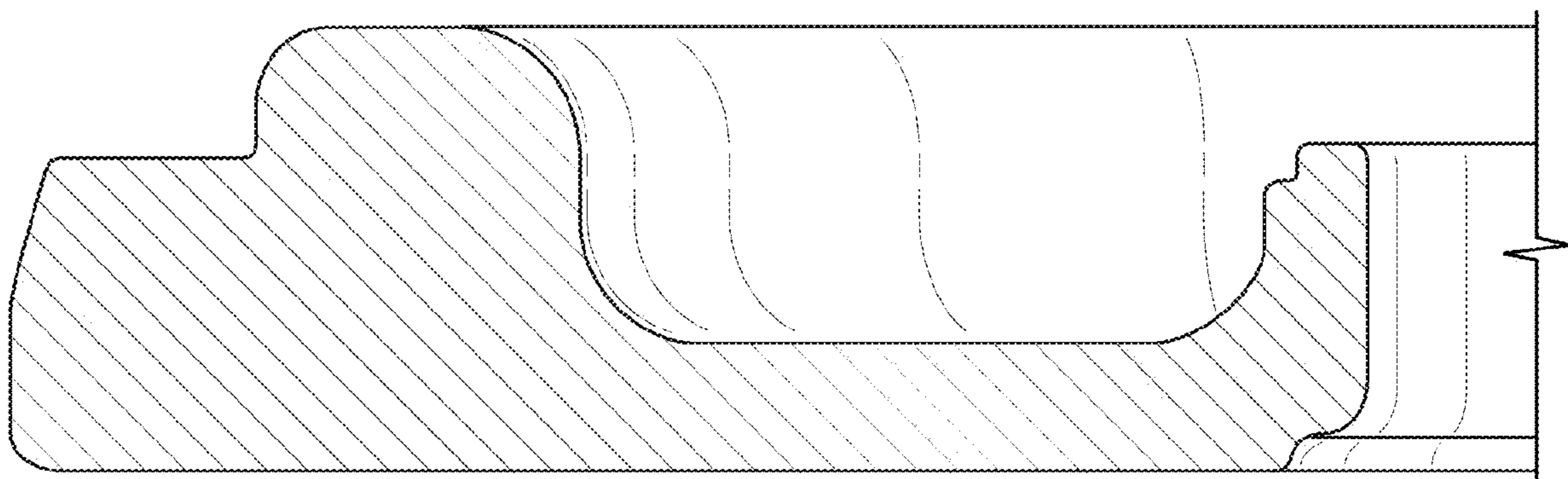
**FIG. 5**



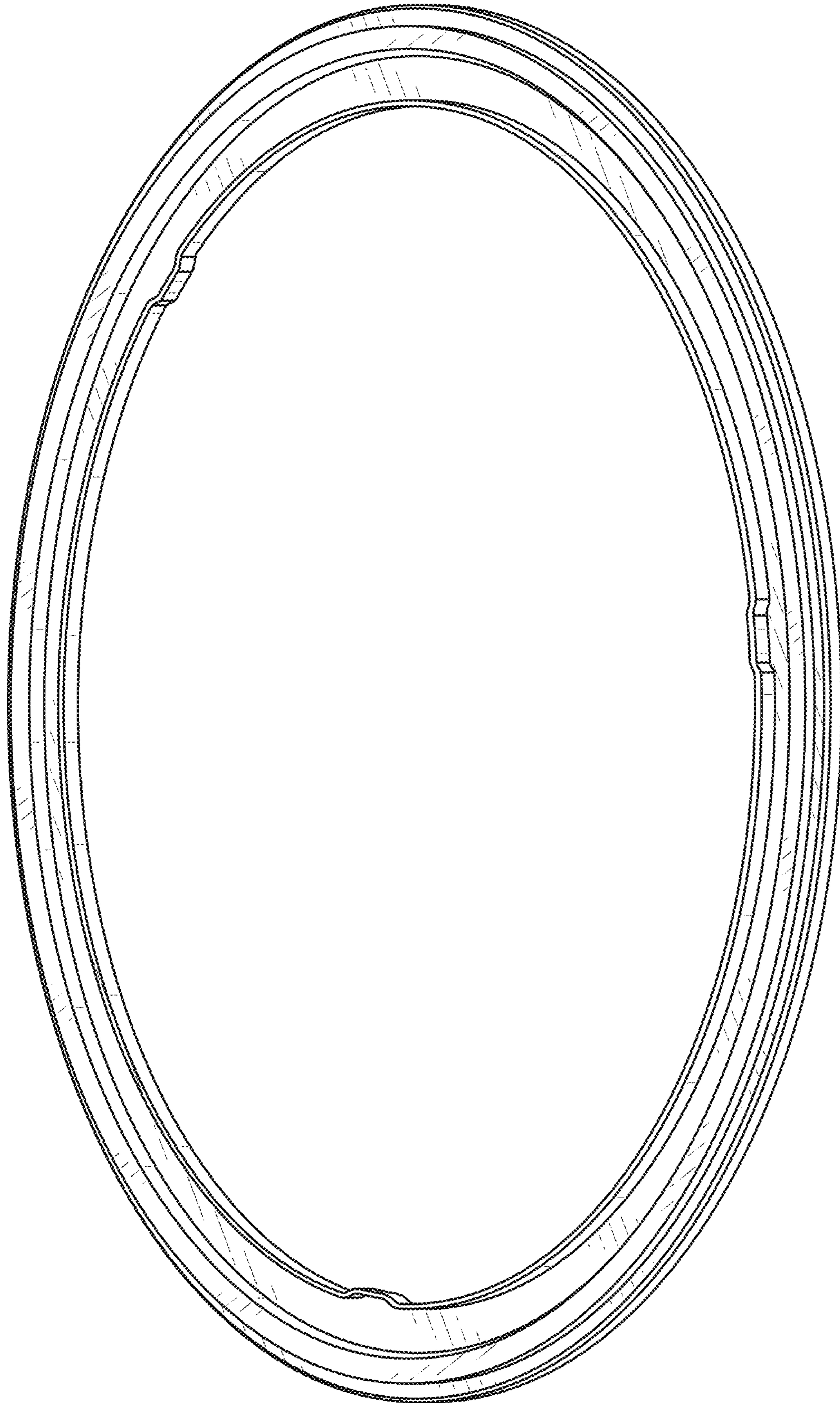
**FIG. 6**



**FIG. 7**

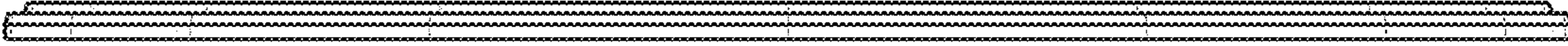


**FIG. 8**

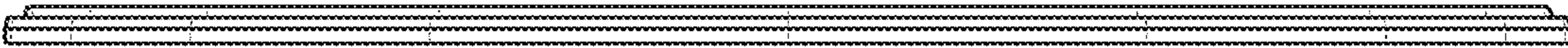


**FIG. 9**

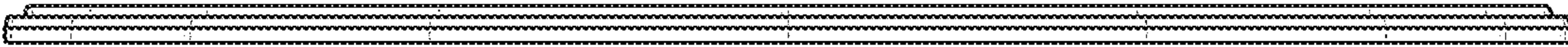




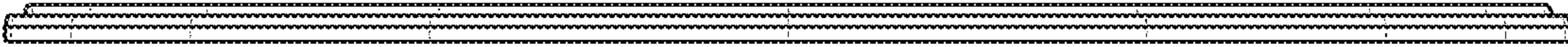
**FIG. 10**



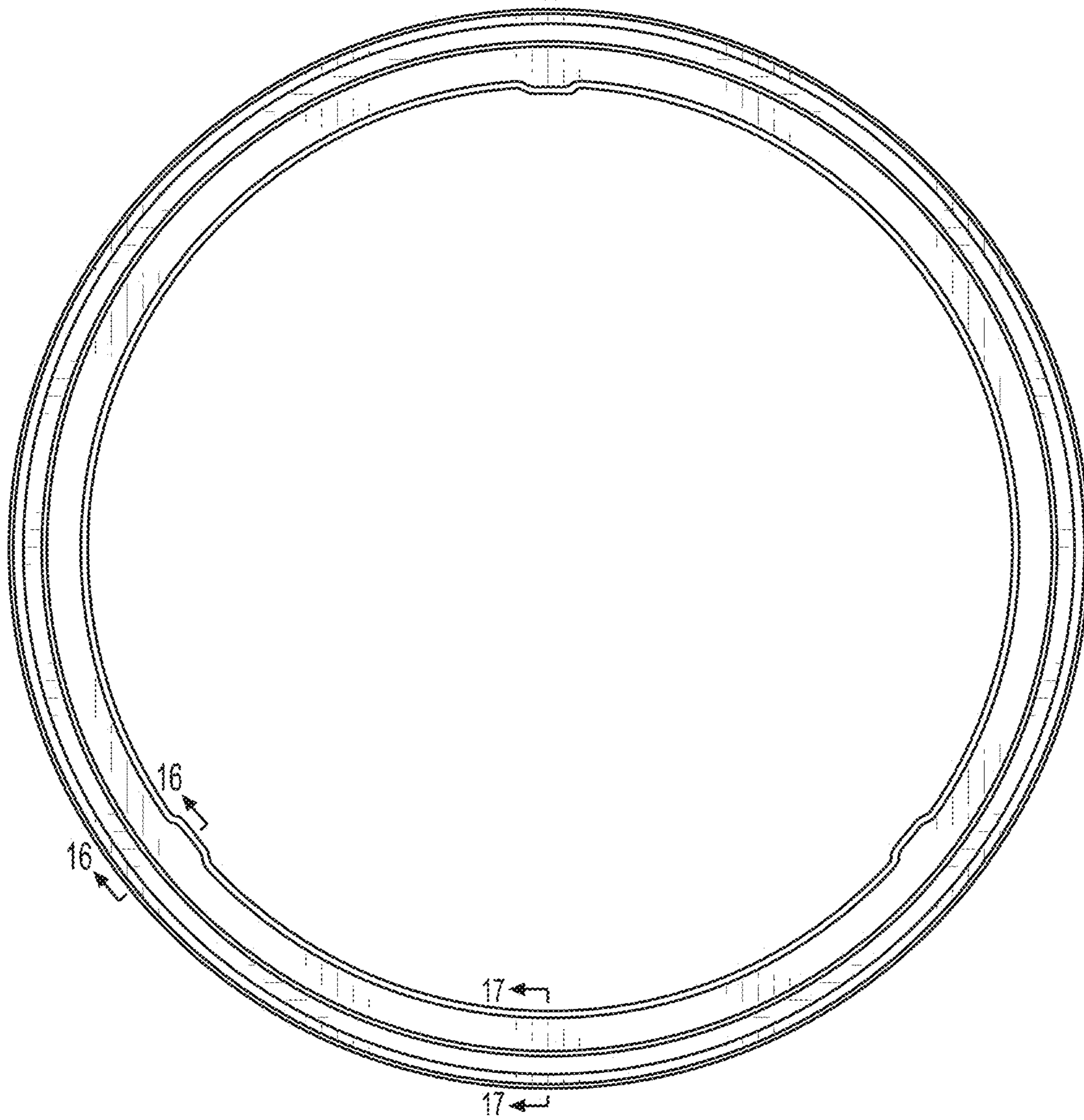
**FIG. 11**



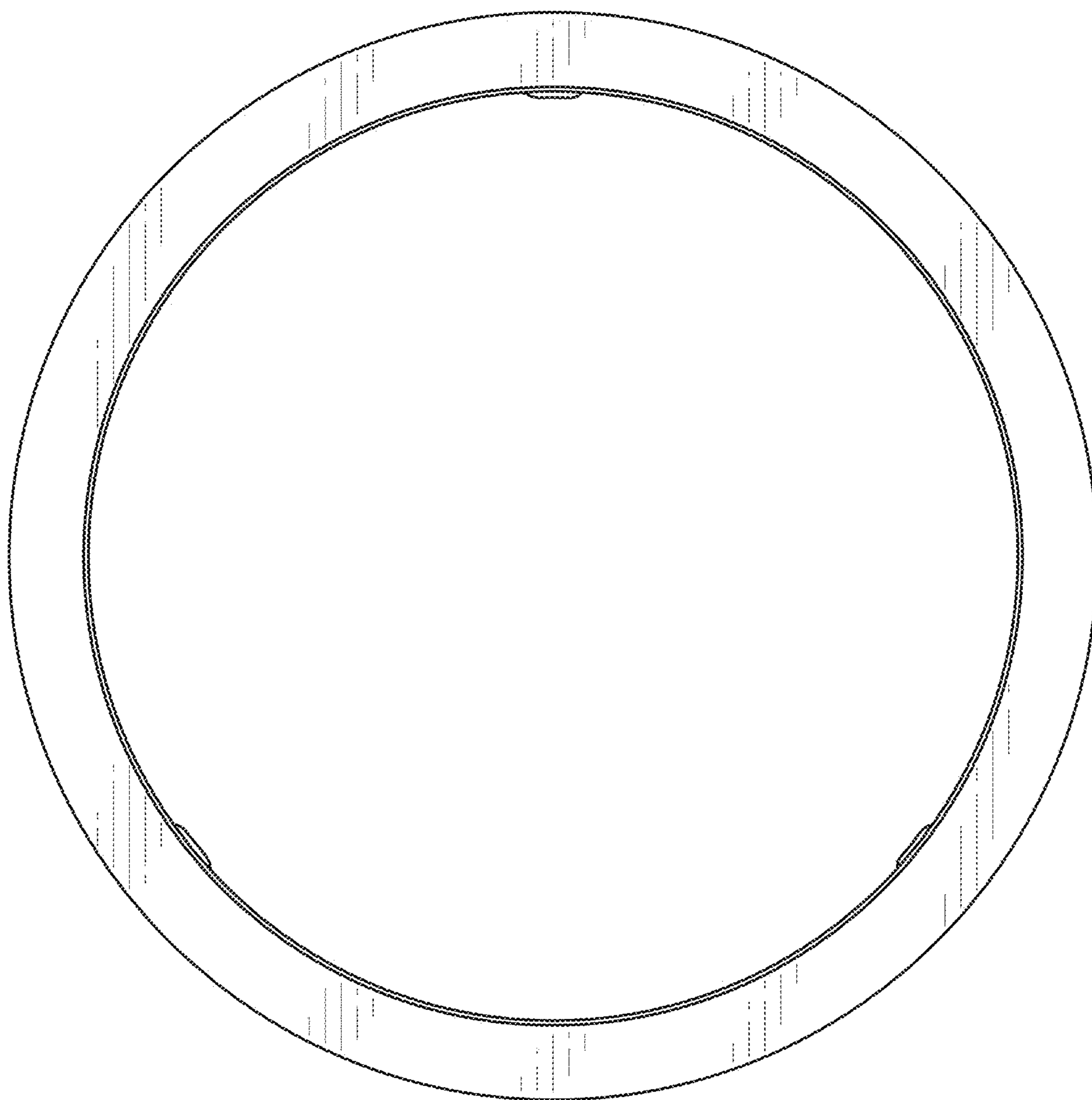
**FIG. 12**



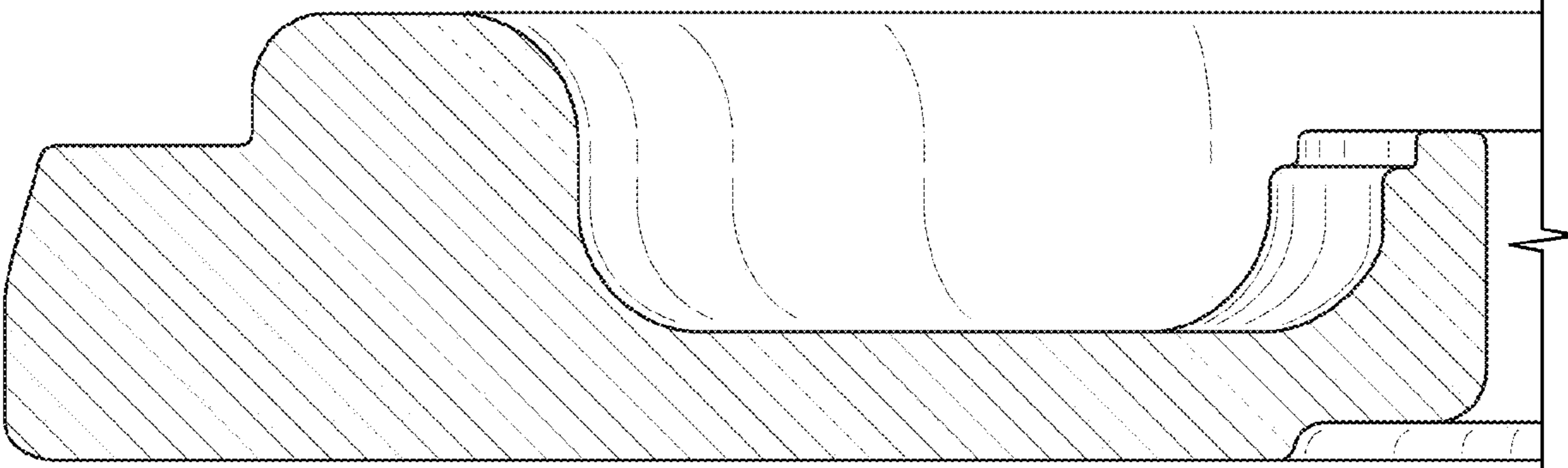
**FIG. 13**



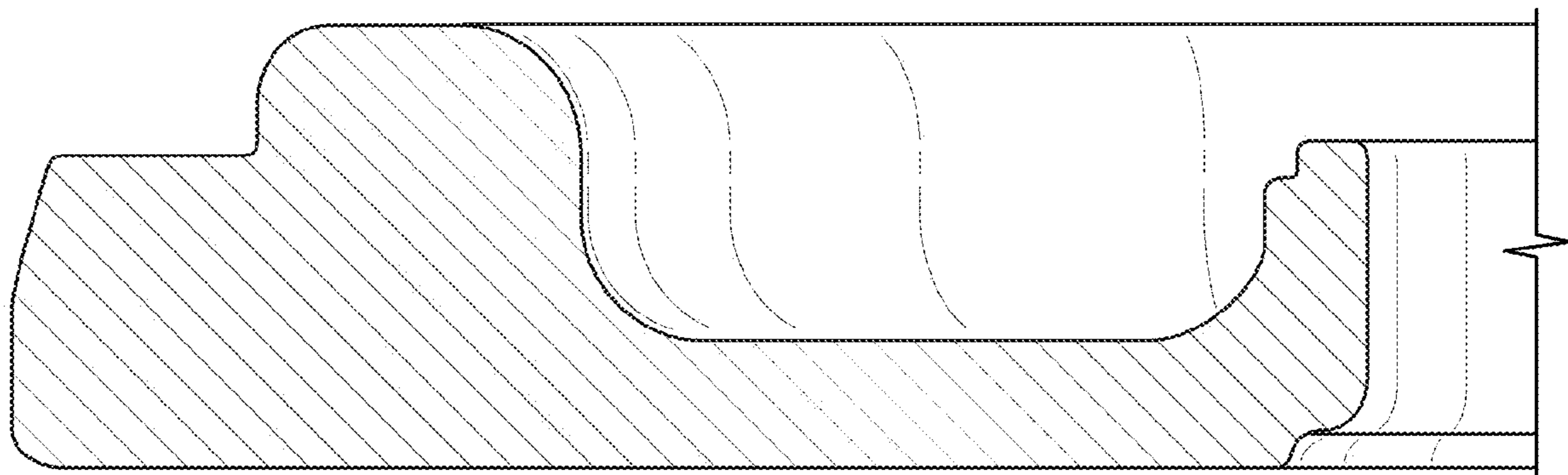
**FIG. 14**



**FIG. 15**



**FIG. 16**



**FIG. 17**